



#### THERMAL CHARACTERISTICS

Parameter	Symbol	Max	Units
Junction-to-Case - Steady State (Note 2)	R <sub>JC</sub>	1.08	′ C/M
Junction-to-Ambient - Steady State (Notes 1, 2)	R <sub>JA</sub>	43	, C/W

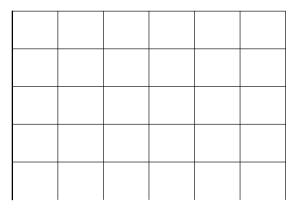
### **ELECTRICAL CHARACTERISTICS** ( $T_J = 25$ C unless otherwise stated)

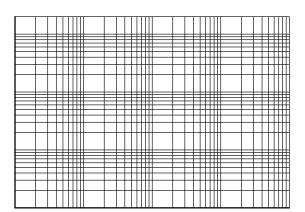
Parameter Symbol Test Condition
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#### **OFF CHARACTERISTICS**

Drain-to-Source Breakdown Voltage V<sub>(BR)DSS</sub>

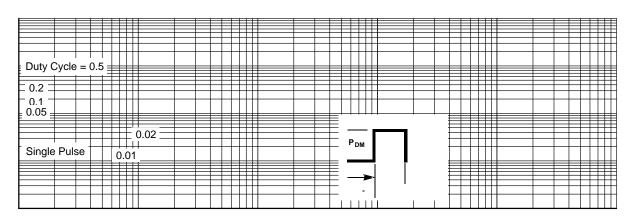
#### **TYPICAL CHARACTERISTICS**





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 $Z_{\theta JC}$ , EFFECTIVE TRANSIENT THERMAL RESISTANCE ( C/W)



t, PULSE TIME (s)

Figure 13. Junction-to-Case Transient Thermal Response



#### H-PSOF8L 9.90x10.38x2.30, 1.20P CASE 100DC ISSUE D

**DATE 30 JUL 2024** 

D4 (2x)

LAND PATTERN RECOMMENDATION



H/2

# GENERIC MARKING DIAGRAM\*

XXXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week

= Assembly Lot Code

ZZ



\*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

